

2N7002

60 V, 300 mA N-channel Trench MOSFET

Rev. 7 — 8 September 2011

Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Suitable for logic level gate drive sources
- Surface-mounted package
- Very fast switching
- Trench MOSFET technology

1.3 Applications

- Logic level translators
- High-speed line drivers

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 150\text{ °C}$	-	-	60	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{sp} = 25\text{ °C}$; see Figure 1 ; see Figure 3	-	-	300	mA
P_{tot}	total power dissipation	$T_{sp} = 25\text{ °C}$; see Figure 2	-	-	0.83	W
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 500\text{ mA}$; $T_j = 25\text{ °C}$; see Figure 6 ; see Figure 8	-	2.8	5	Ω

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	<p>SOT23 (TO-236AB)</p>	<p>mbb076</p>
2	S	source		
3	D	drain		



3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
2N7002	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
2N7002	12%

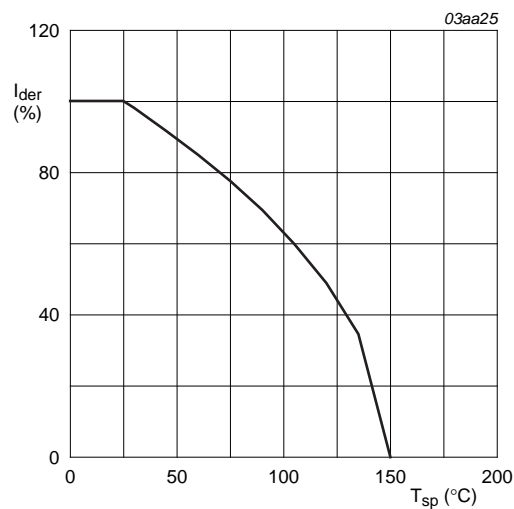
[1] % = placeholder for manufacturing site code

5. Limiting values

Table 5. Limiting values

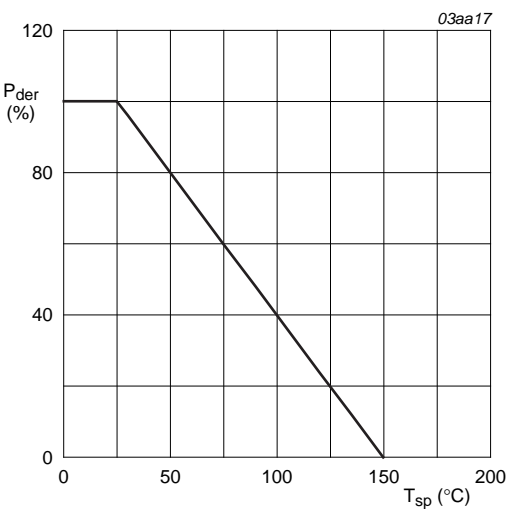
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 150\text{ °C}$	-	60	V
V_{DGR}	drain-gate voltage	$25\text{ °C} \leq T_j \leq 150\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$	-	60	V
V_{GS}	gate-source voltage		-30	30	V
V_{GSM}	peak gate-source voltage	pulsed; $t_p \leq 50\text{ }\mu\text{s}$; $\delta = 0.25$	-40	40	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{sp} = 25\text{ °C}$; see Figure 1 ; see Figure 3	-	300	mA
		$V_{GS} = 10\text{ V}$; $T_{sp} = 100\text{ °C}$; see Figure 1	-	190	mA
I_{DM}	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{sp} = 25\text{ °C}$; see Figure 3	-	1.2	A
P_{tot}	total power dissipation	$T_{sp} = 25\text{ °C}$; see Figure 2	-	0.83	W
T_j	junction temperature		-65	150	°C
T_{stg}	storage temperature		-65	150	°C
Source-drain diode					
I_S	source current	$T_{sp} = 25\text{ °C}$	-	300	mA
I_{SM}	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{sp} = 25\text{ °C}$	-	1.2	A



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of solder point temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of solder point temperature

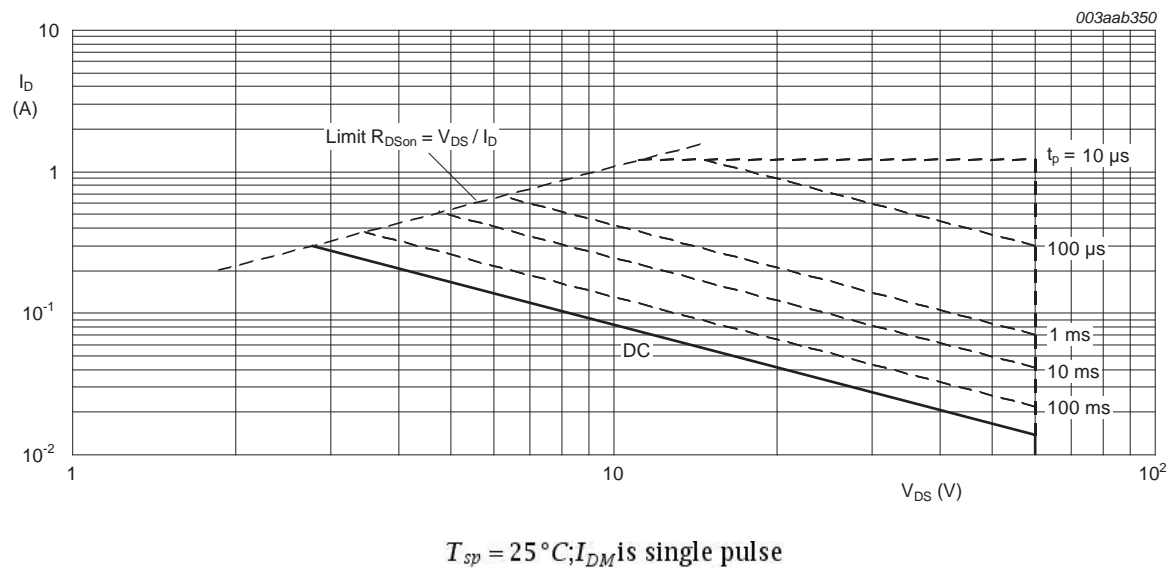


Fig 3. Safe operating area; continous and peak drain currents as a function of drain-source voltage

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	Mounted on a printed-circuit board; minimum footprint ; vertical in still air	-	-	350	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point	see Figure 4	-	-	150	K/W

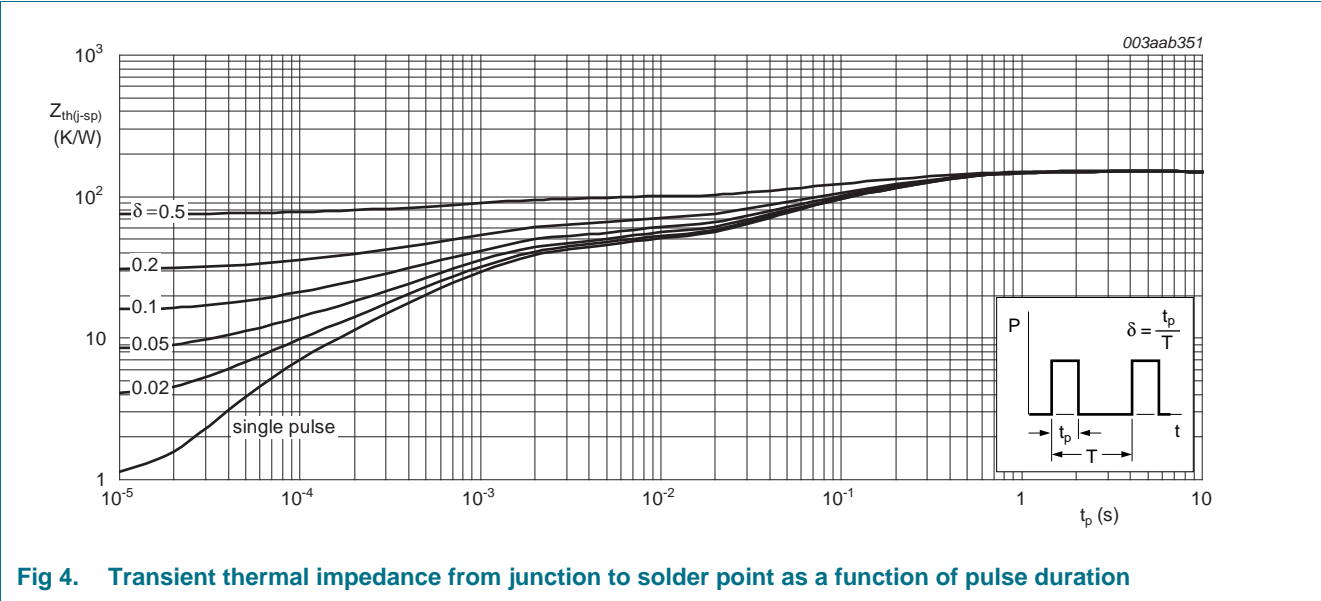


Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration

7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 10 μA; V _{GS} = 0 V; T _j = 25 °C	60	-	-	V
		I _D = 10 μA; V _{GS} = 0 V; T _j = -55 °C	55	-	-	V
V _{GStH}	gate-source threshold voltage	I _D = 0.25 mA; V _{DS} = V _{GS} ; T _j = 25 °C; see Figure 9 ; see Figure 10	1	2	2.5	V
		I _D = 0.25 mA; V _{DS} = V _{GS} ; T _j = 150 °C; see Figure 9 ; see Figure 10	0.6	-	-	V
		I _D = 0.25 mA; V _{DS} = V _{GS} ; T _j = -55 °C; see Figure 9 ; see Figure 10	-	-	2.75	V
I _{DSS}	drain leakage current	V _{DS} = 48 V; V _{GS} = 0 V; T _j = 25 °C	-	0.01	1	μA
		V _{DS} = 48 V; V _{GS} = 0 V; T _j = 150 °C	-	-	10	μA
I _{GSS}	gate leakage current	V _{GS} = 15 V; V _{DS} = 0 V; T _j = 25 °C	-	10	100	nA
		V _{GS} = -15 V; V _{DS} = 0 V; T _j = 25 °C	-	10	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 500 mA; T _j = 25 °C; see Figure 6 ; see Figure 8	-	2.8	5	Ω
		V _{GS} = 10 V; I _D = 500 mA; T _j = 150 °C; see Figure 6 ; see Figure 8	-	-	9.25	Ω
		V _{GS} = 4.5 V; I _D = 75 mA; T _j = 25 °C; see Figure 6 ; see Figure 8	-	3.8	5.3	Ω
Dynamic characteristics						
C _{iss}	input capacitance	V _{DS} = 10 V; f = 1 MHz; V _{GS} = 0 V; T _j = 25 °C	-	31	50	pF
C _{oss}	output capacitance		-	6.8	30	pF
C _{rss}	reverse transfer capacitance		-	3.5	10	pF
t _{on}	turn-on time	V _{GS} = 10 V; V _{DS} = 50 V; R _L = 250 Ω;	-	2.5	10	ns
t _{off}	turn-off time	R _{G(ext)} = 50 Ω; R _{GS} = 50 Ω	-	11	15	ns
Source-drain diode						
V _{SD}	source-drain voltage	I _S = 300 mA; V _{GS} = 0 V; T _j = 25 °C; see Figure 11	-	0.85	1.5	V
Q _r	recovered charge	V _{GS} = 0 V; I _S = 300 mA;	-	30	-	nC
t _{rr}	reverse recovery time	dI _S /dt = -100 A/μs	-	30	-	ns

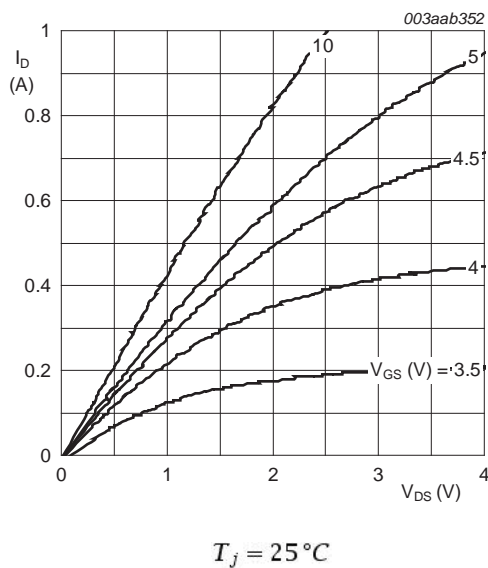


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

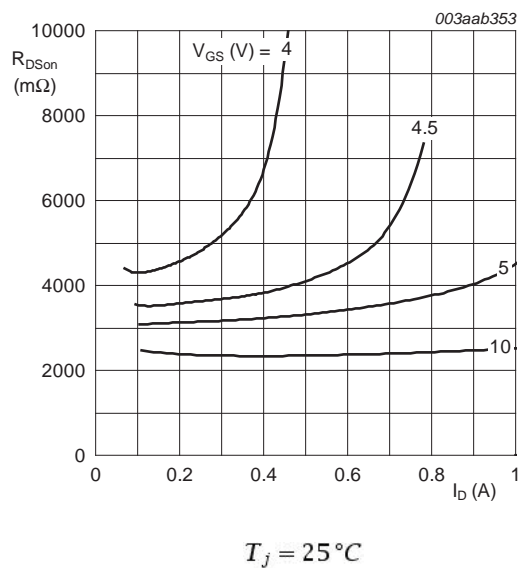


Fig 6. Drain-source on-state resistance as a function of drain current; typical values

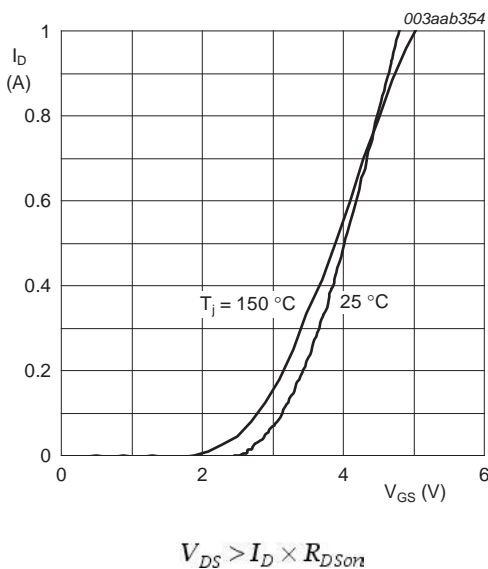


Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values

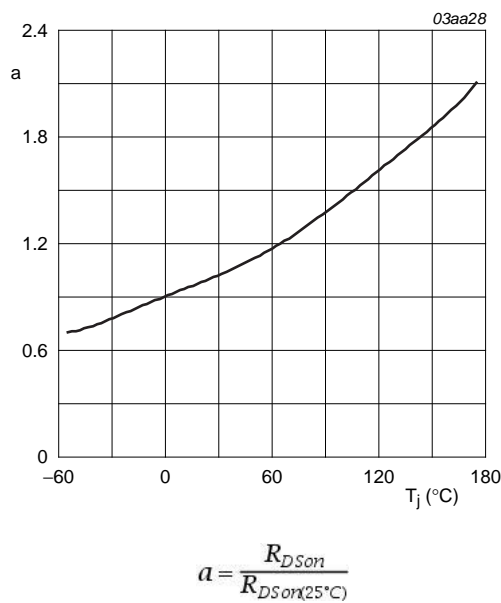


Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature

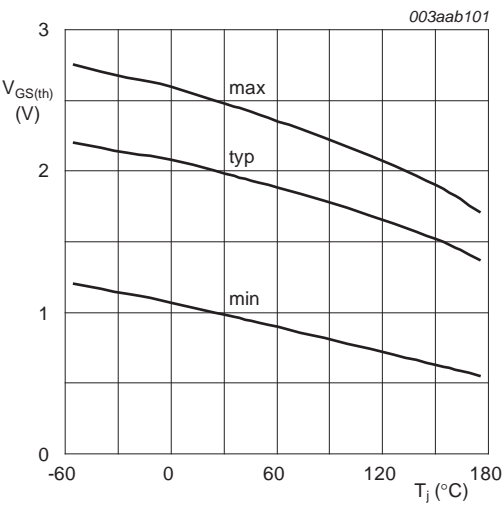


Fig 9. Gate-source threshold voltage as a function of junction temperature

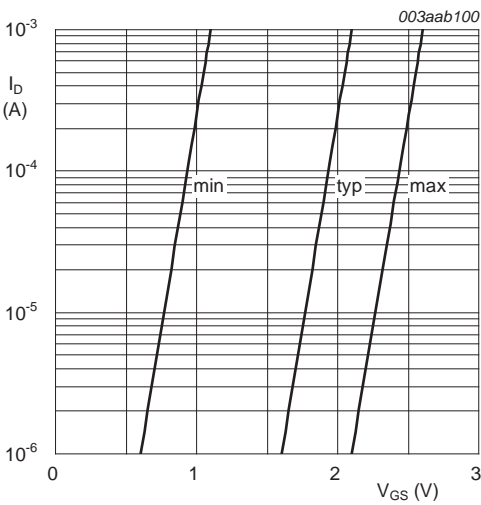


Fig 10. Sub-threshold drain current as a function of gate-source voltage

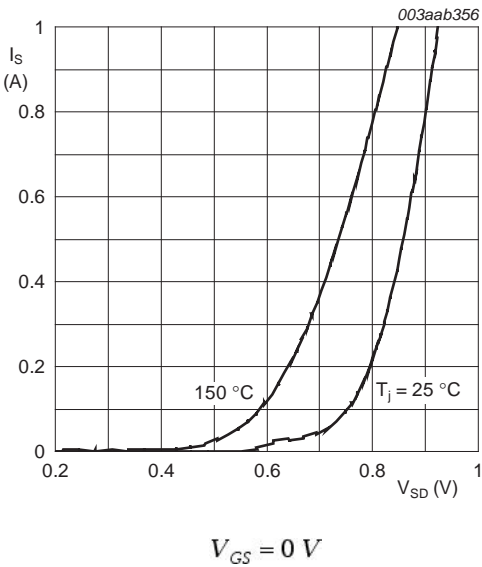


Fig 11. Source current as a function of source-drain voltage; typical values

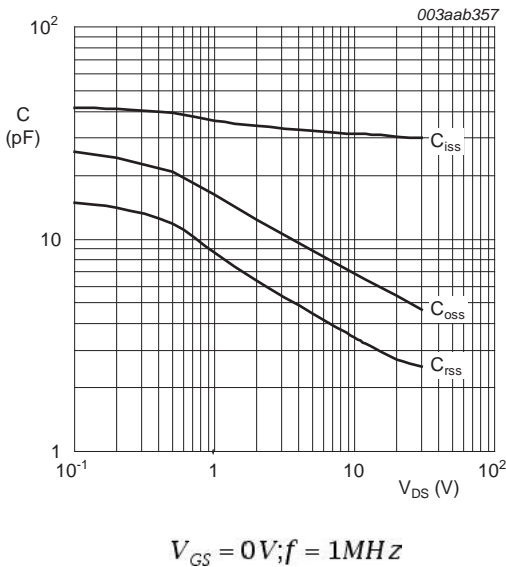


Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

8. Package outline

Plastic surface-mounted package; 3 leadsSOT23

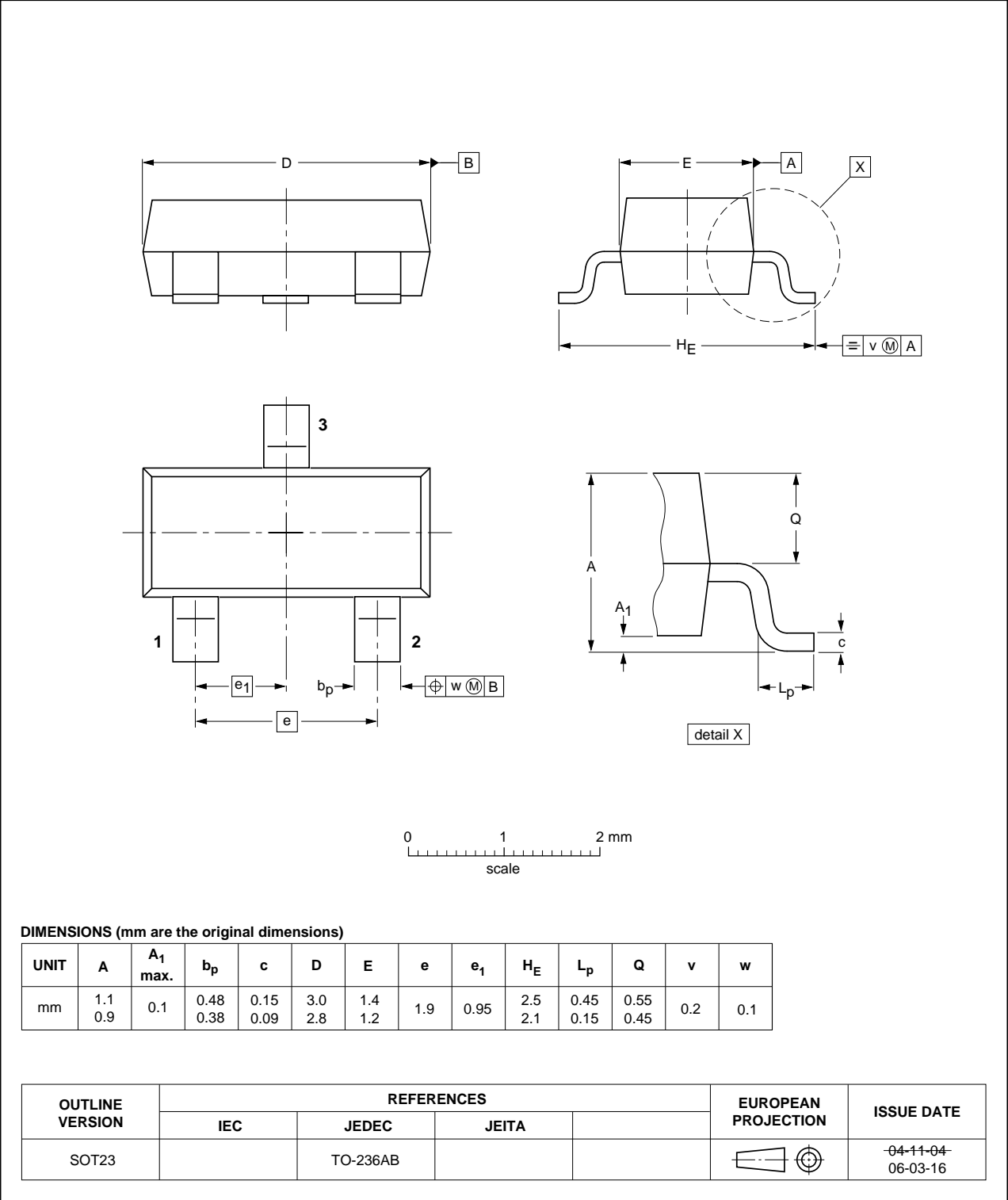
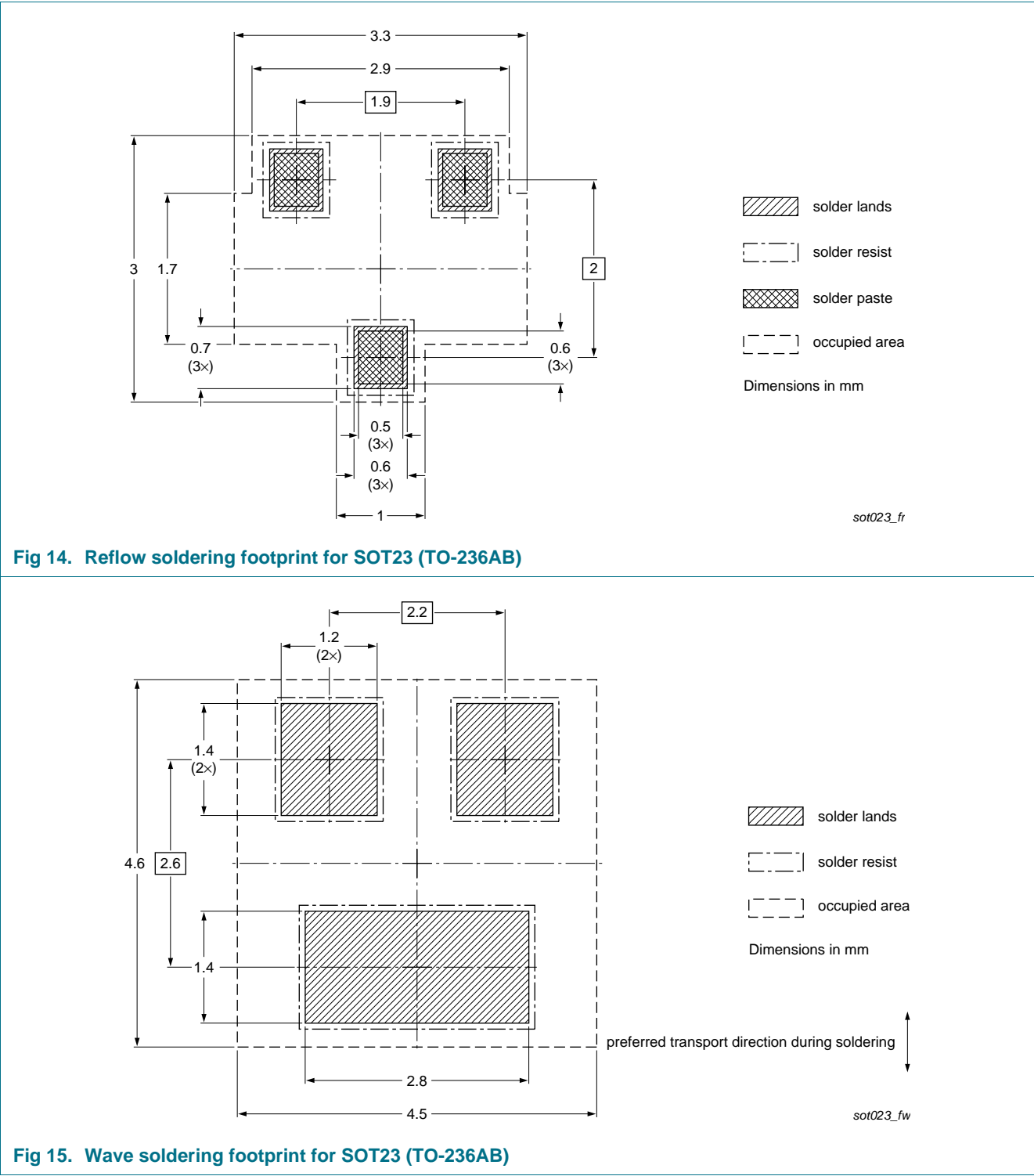


Fig 13. Package outline SOT23 (TO-236AB)

9. Soldering



10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2N7002 v.7	20110908	Product data sheet	-	2N7002 v.6
Modifications:	<ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate.			
2N7002 v.6	20060428	Product data sheet		2N7002 v.5
2N7002 v.5	20051115	Product data sheet		2N7002 v.4
2N7002 v.4	20050426	Product data sheet		2N7002 v.3
2N7002 v.3	20000727	Product specification	HZG336	2N7002 v.2
2N7002 v.2	19970617	Product specification		2N7002 v.1
2N7002 v.1	19901031	Product specification	-	-

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Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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